

Date Mailed: September 29, 2003

FORM 1449*

INFORMATION DISCLOSURE STATEMENT

IN AN APPLICATION

(Use several sheets if necessary)

Docket Number:
HSJ920030097US1

Application Number:
unassigned

Applicant: ALBRECHT et al.

Filing Date: 0929/2003

Group Art Unit: unassigned

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
A2	4,488,192	12/11/1984	TRESEDER			
	4,521,668	06/04/1985	OSIAL et al.			
	4,665,294	05/12/1987	HIRA et al.			
	4,760,240	07/26/1988	IIKAWA et al.			
	5,109,594	05/05/1992	SHARP et al.			
	5,298,683	03/28/1994	TAYLOR			
	5,392,177	02/21/1995	CHAINER et al.			
	5,405,272	04/11/1995	RAPOZA			
	5,454,157	10/03/1995	ANANTH et al.			
	5,596,486	01/21/1997	YOUNG et al.			
	5,811,756	09/22/1998	HORITA et al.			
	5,940,279	08/17/1999	GADEMANN et al.			
	6,355,362	03/12/2002	JONES et al.			
	6,392,838	05/21/2002	HEARN et al.			
	6,430,000	08/06/2002	RENT			

FOREIGN PATENT DOCUMENTS

	DOCUMENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
A2	JP 62071078	04.01.1987	JP			(abstract only)	
	JP 07-006577	10.01.1995	JP			(abstract only)	
	JP 08-161881	21.06.1996	JP			(abstract only)	

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

August 1992	"High I/O Hermetic Interconnect for Aluminum Modules," IBM Technical Disclosure Bulletin, EN8920038 (340), August 1992.

EXAMINER

A. Heinz

DATE CONSIDERED

4/3/05

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form for next communication to the Applicant.

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